

DESCRIPTION

The KI2301 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

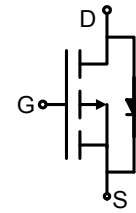
GENERAL FEATURES

- High Power and current handling capability
- Lead free product is acquired
- Surface Mount Package

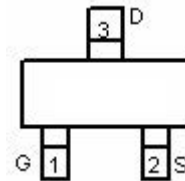
| V_{DSS} | $R_{DS(ON)}$ @-4.5V(Typ) | $R_{DS(ON)}$ @-2.5V(Typ) | I_D |
|-----------|-----------------------------|-----------------------------|-------|
| -20V | 64m Ω | 89 m Ω | -3A |

Application

- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOT-23

Absolute Maximum Ratings (TA=25°C unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------|-------------|
| Drain-Source Voltage | V_{DS} | -20 | V |
| Gate-Source Voltage | V_{GS} | ± 12 | V |
| Drain Current-Continuous | I_D | -3 | A |
| Drain Current -Pulsed (Note 1) | I_{DM} | -10 | A |
| Maximum Power Dissipation | P_D | 1 | W |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^{\circ}C$ |

Thermal Characteristic

| | | | |
|--|-----------------|-----|---------------|
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 125 | $^{\circ}C/W$ |
|--|-----------------|-----|---------------|

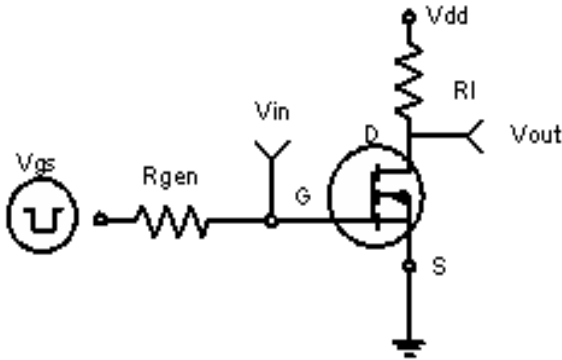
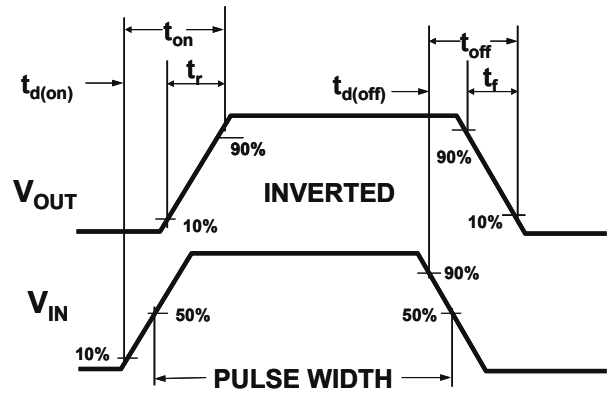
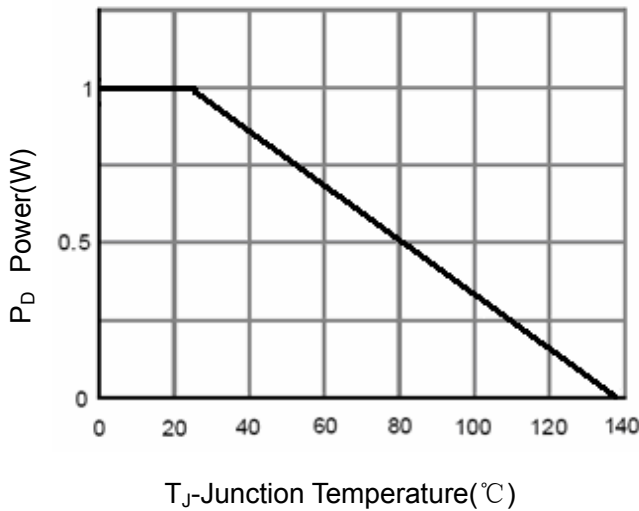
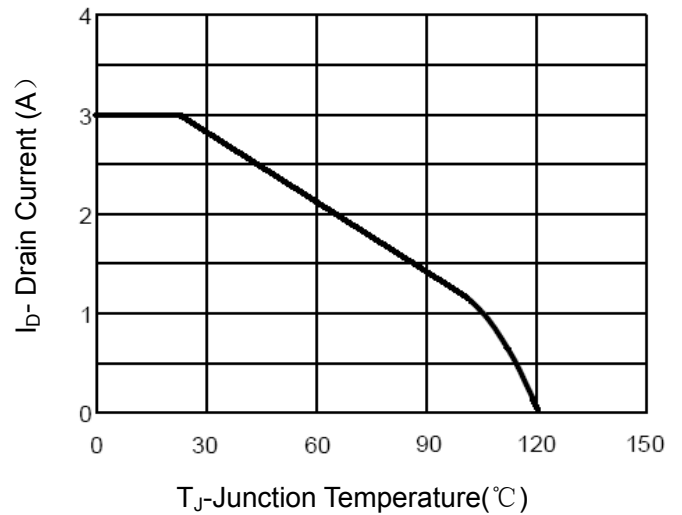
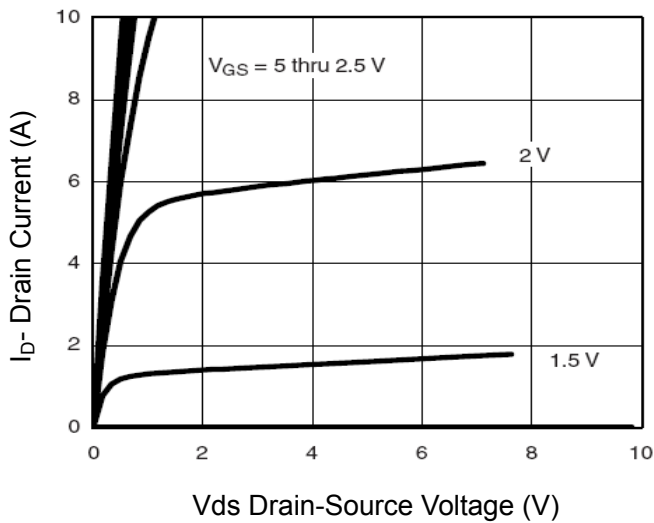
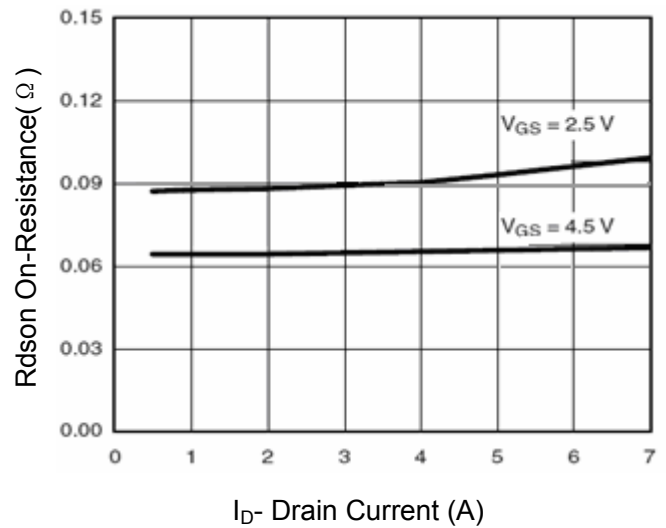
Electrical Characteristics (TA=25°C unless otherwise noted)

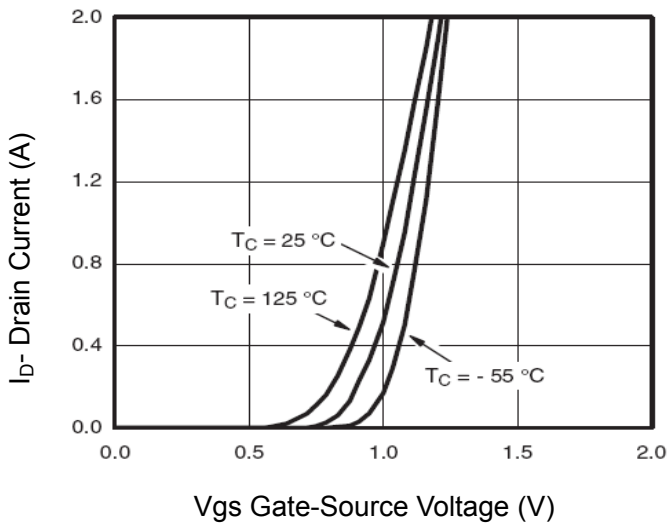
| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---------------------------------|------------|----------------------------|-----|-----|-----|---------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS}=0V, I_D=-250\mu A$ | -20 | -24 | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS}=-20V, V_{GS}=0V$ | - | - | -1 | μA |

| | | | | | | |
|---|--------------|--|------|------|-----------|------------|
| Gate-Body Leakage Current | I_{GSS} | $V_{GS}=\pm 12V, V_{DS}=0V$ | - | - | ± 100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS}=V_{GS}, I_D=-250\mu A$ | -0.4 | -0.7 | -1 | V |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | $V_{GS}=-4.5V, I_D=-3A$ | - | 64 | 110 | m Ω |
| | | $V_{GS}=-2.5V, I_D=-2A$ | - | 89 | 140 | m Ω |
| Forward Transconductance | g_{FS} | $V_{DS}=-5V, I_D=-2.8A$ | - | 9.5 | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C_{iss} | $V_{DS}=-10V, V_{GS}=0V,$ $F=1.0MHz$ | - | 405 | - | PF |
| Output Capacitance | C_{oss} | | - | 75 | - | PF |
| Reverse Transfer Capacitance | C_{rss} | | - | 55 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | $t_{d(on)}$ | $V_{DD}=-10V, I_D=-1A$ $V_{GS}=-4.5V, R_{GEN}=10\Omega$ | - | 11 | - | nS |
| Turn-on Rise Time | t_r | | - | 35 | - | nS |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 30 | - | nS |
| Turn-Off Fall Time | t_f | | - | 10 | - | nS |
| Total Gate Charge | Q_g | $V_{DS}=-10V, I_D=-3A,$ $V_{GS}=-2.5V$ | - | 3.3 | 12 | nC |
| Gate-Source Charge | Q_{gs} | | - | 0.7 | - | nC |
| Gate-Drain Charge | Q_{gd} | | - | 1.3 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V_{SD} | $V_{GS}=0V, I_S=1.3A$ | - | - | -1.2 | V |
| Diode Forward Current (Note 2) | I_S | | - | - | -1.3 | A |

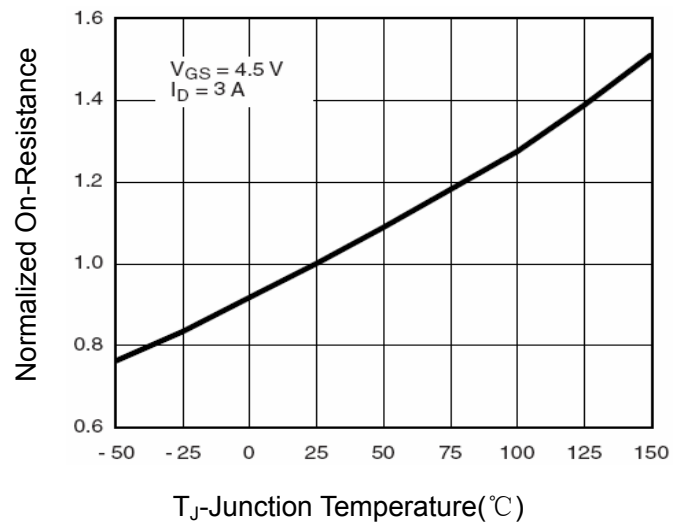
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production

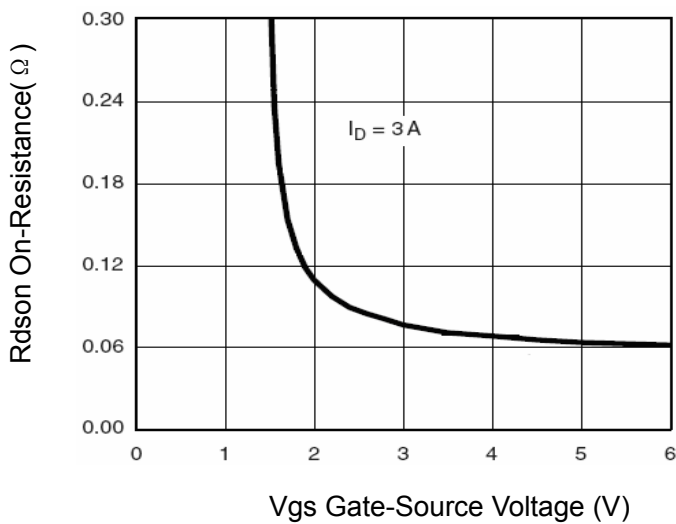
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

Figure 1: Switching Test Circuit

Figure 2: Switching Waveforms

Figure 3 Power Dissipation

Figure 4 Drain Current

Figure 5 Output CHARACTERISTICS

Figure 6 Drain-Source On-Resistance



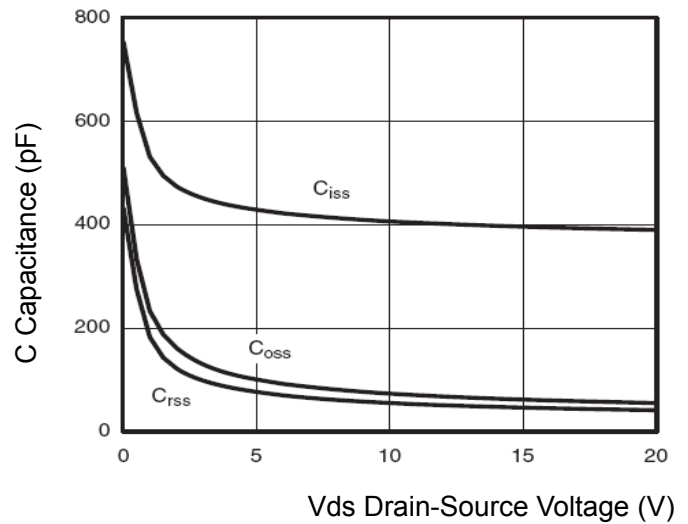
Vgs Gate-Source Voltage (V)
Figure 7 Transfer Characteristics



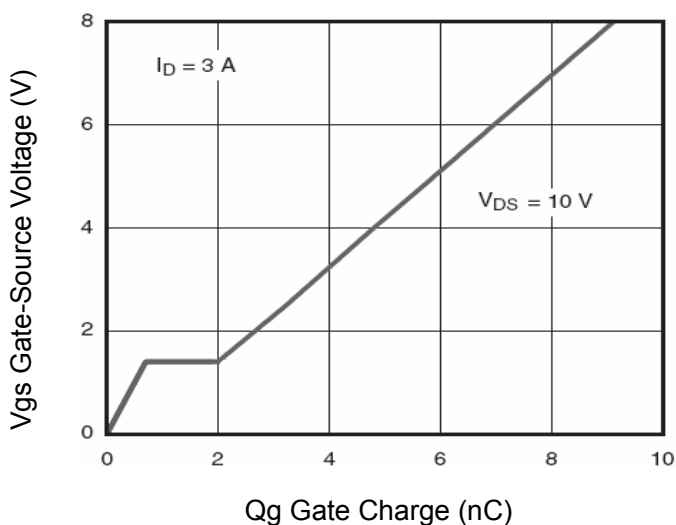
T_J-Junction Temperature(°C)
Figure 8 Drain-Source On-Resistance



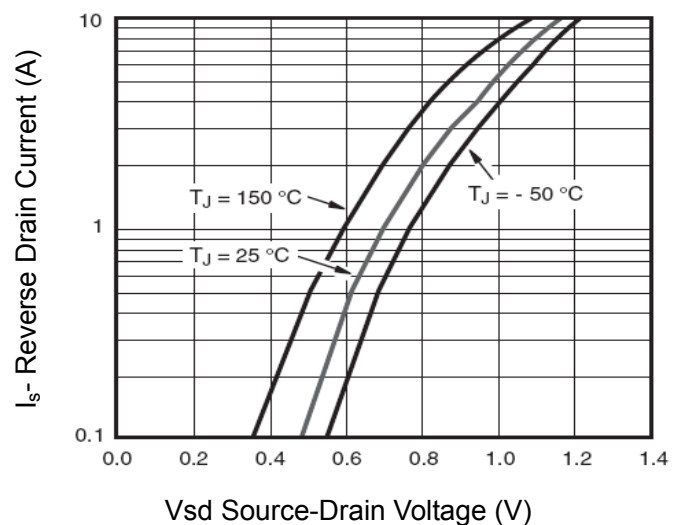
Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds



Qg Gate Charge (nC)
Figure 11 Gate Charge



Vsd Source-Drain Voltage (V)
Figure 12 Source- Drain Diode Forward

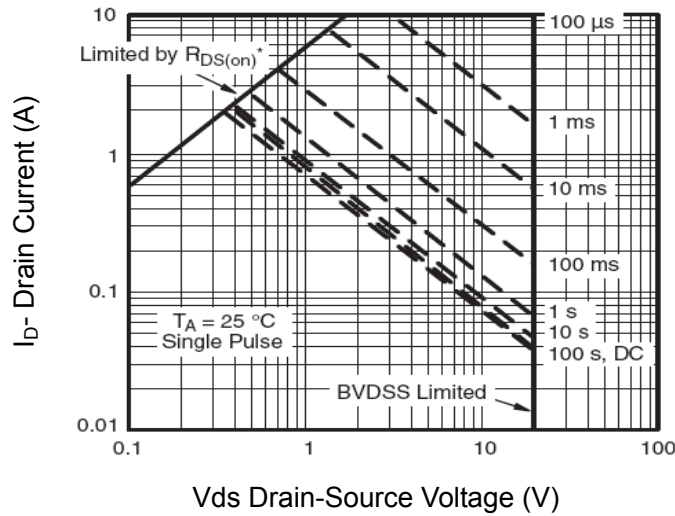


Figure 13 Safe Operation Area

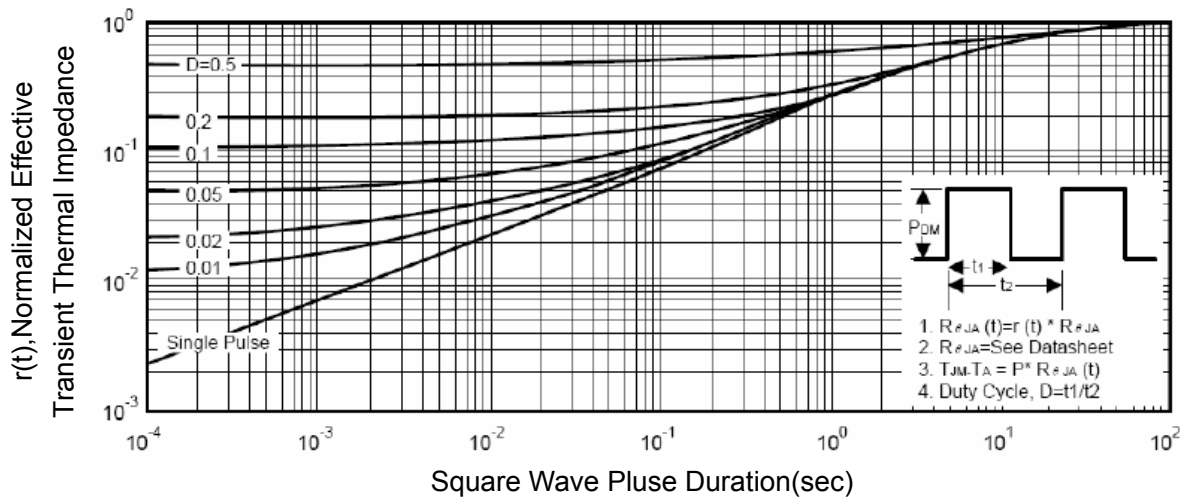


Figure 14 Normalized Maximum Transient Thermal Impedance